

CHEMLINQ™ MCL-C11

Melamine Cleaning Compound - Tablets



- Strong cleaning performance
- Compatible with wide range of mold cavity designs
- Increases mold lifespan and improves productivity

CHEMLINQ™ MCL-C11 is a mold cleaning compound (tablet) composed of melamine resin, silica filler, and other additives. It is specifically formulated to remove epoxy molding compound residues and stains from metal mold dies. **CHEMLINQ™ MCL-C11** has high cohesive strength and optimized rheological properties. It effectively restores mold surface integrity, prolongs tooling lifespan, and significantly reduces mold cleaning cycle times, minimizing production downtime. Overall, this compression grade product is well-suited for cleaning mold dies in semiconductor packaging, where clean surfaces are essential for consistent quality and yield.

CHEMLINQ™ MCL-C11 can be used alone or partnered with CHEMLINQ™ RCS rubber cleaning sheet series to enhance cleaning performance.

Specifications

Property	Value	Unit
Appearance	White tablets	–
Specific Gravity	1.2–1.5	–
Density	1.1–1.3	g/cm ³
Disc Flow	80–130	mm
Size & Weight		
Length	68	mm
Width	38	mm
Weight	15 or 20	g

Recommend Processing Parameters

Parameter	Value	Unit
Cure Temperature	160–190	°C
Cure Time	300–500	s
Mold Clamp Pressure	20–150	ton

Europe

Industrieweg 15E,
1566JN Assendelft
The Netherlands
Phone: +31 (20) 893 2224
Email: info@caplinq.com

Canada

80 Sirocco Crescent
Ottawa ON, K2S 2C9
Canada
Phone: +1 (613) 482-2215
Email: info@caplinq.com



North America

36927 Schoolcraft Rd
Livonia, MI 48150
United States
Phone: +1 (313) 558-8243
Email: info@caplinq.com

South East Asia

S-08-07 Persiaran Triangle
B Lepas, Penang 11900
Malaysia
Phone: +60 (12) 4302223
Email: info@caplinq.com

Preparation

Instructions

1. Make sure the mold temperature is ready for cleaning. Preheat it to its standard operating temperature. Remove all large contaminants prior to cleaning.
2. Place the **MCL-C11** tablets into the mold cavity. The number of tablets depends on the size of the mold and the level of contamination.
3. Close the mold and initiate a standard molding cycle. This includes applying the necessary pressure and heat to activate the cleaning compound. The heat and pressure help the **MCL-C11** tablets to flow across the mold surfaces, effectively loosening and removing organic and inorganic residues.
4. After the cycle is complete, open the mold and eject the cleaning compound residue. Inspect the mold for any remaining contaminants. If necessary, repeat the process using additional tablets or in combination with other cleaning methods, such as **CHEMLINQ™ RCS** rubber cleaning sheets.
5. Perform a final inspection to ensure all residues are removed.

Storage and Handling

CHEMLINQ™ MCL-C11 is packaged in PE bags. Store the product in a cool, dry place, away from heat sources and moisture. Exposure to high humidity and excessive heat can cause curing failures in the cleaning compound. The shelf life is 12 months when stored below 25 °C. If taken from a cold room or refrigerator, thaw it in the sealed package for 18 to 24 hours until it reaches room temperature.

Use the product in a well-ventilated area. Always follow safety guidelines and wear protective equipment when handling. For more safety information, check the Material Safety Data Sheet (MSDS).

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